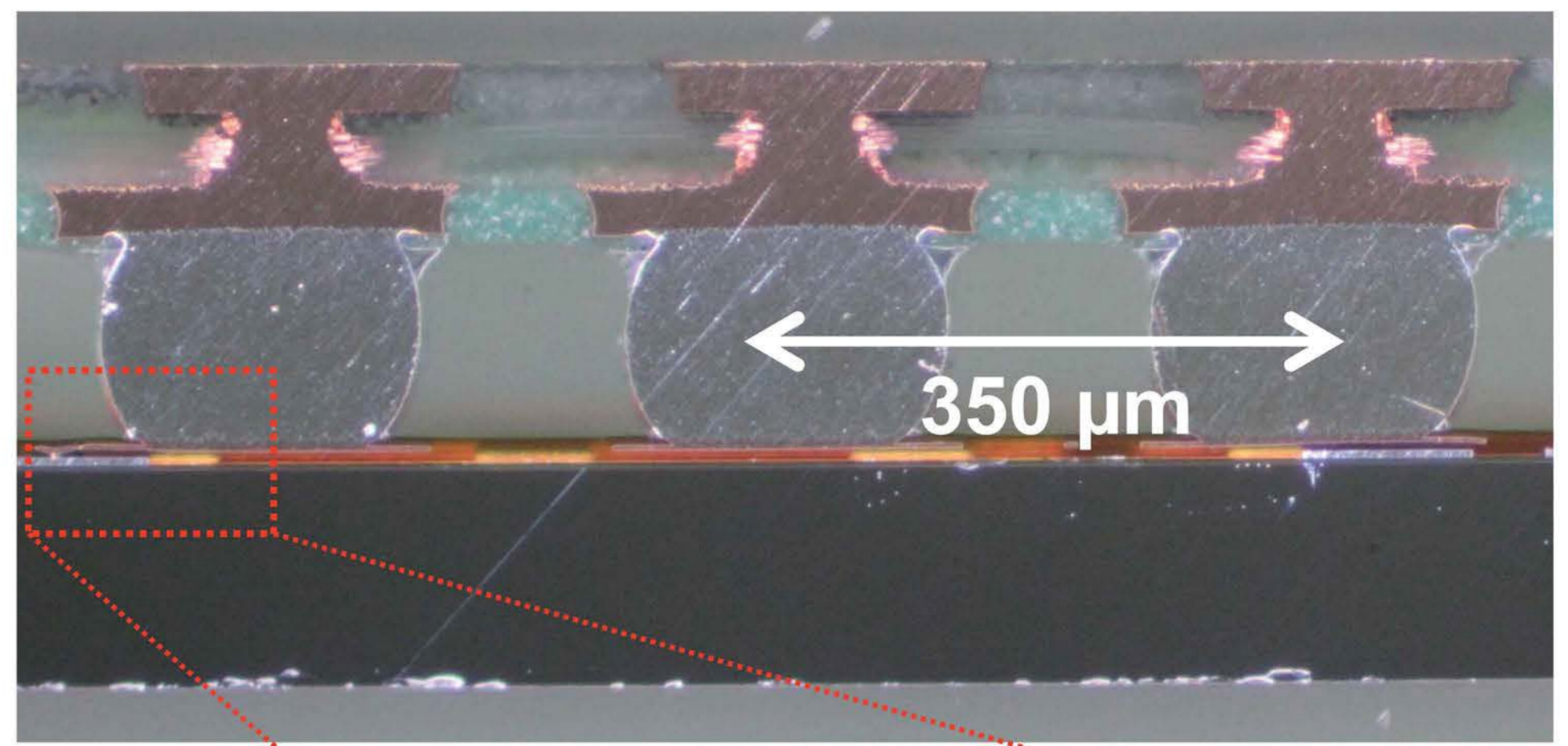
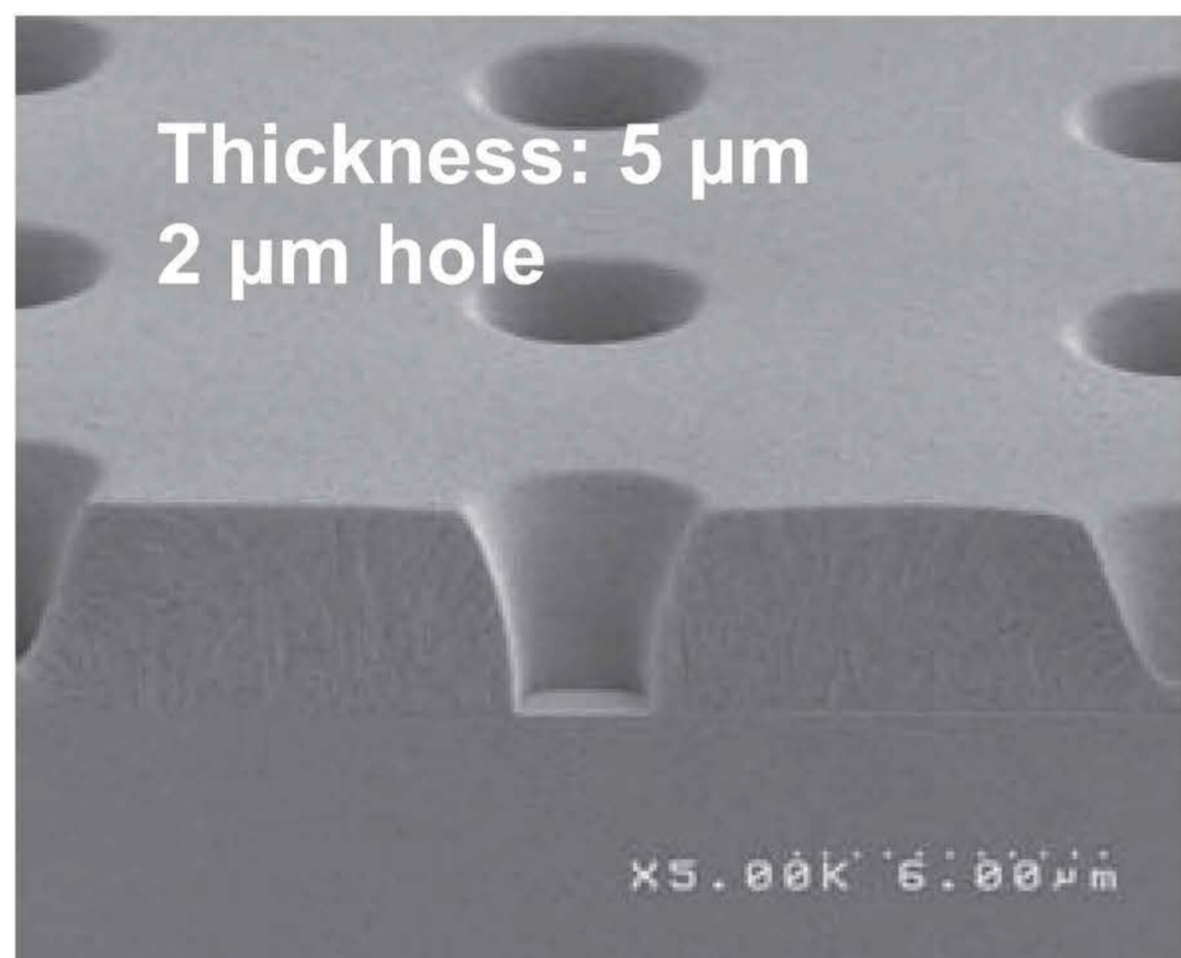


JSR ELPAC™

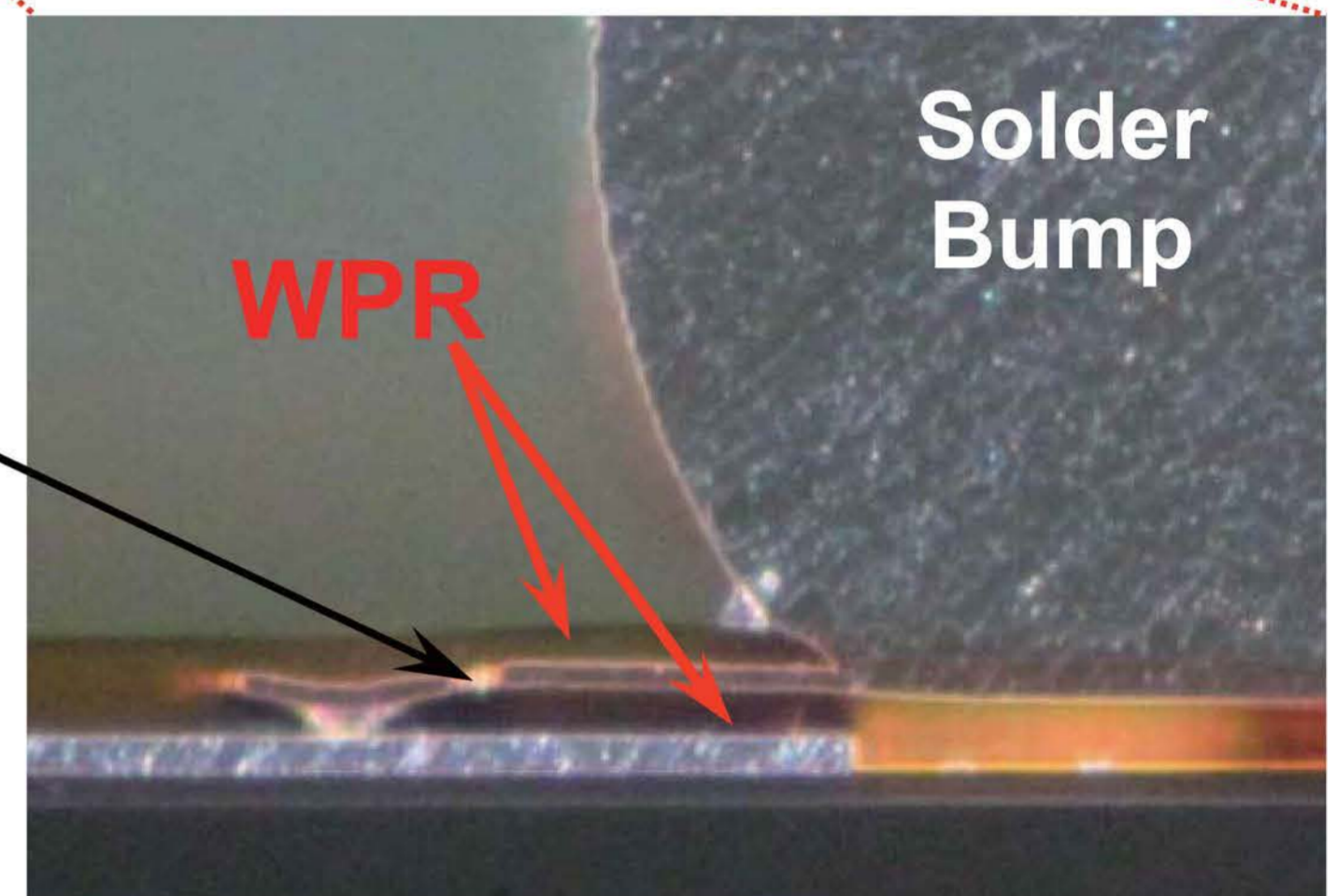
WPR series Photosensitive Dielectric Material

Features

- Low cure temperature (≤ 200 °C)
- High resolution
- Excellent adhesion to SiN, SiO₂
- Excellent insulation reliability
- Low residual stress



Cu Wiring Pattern



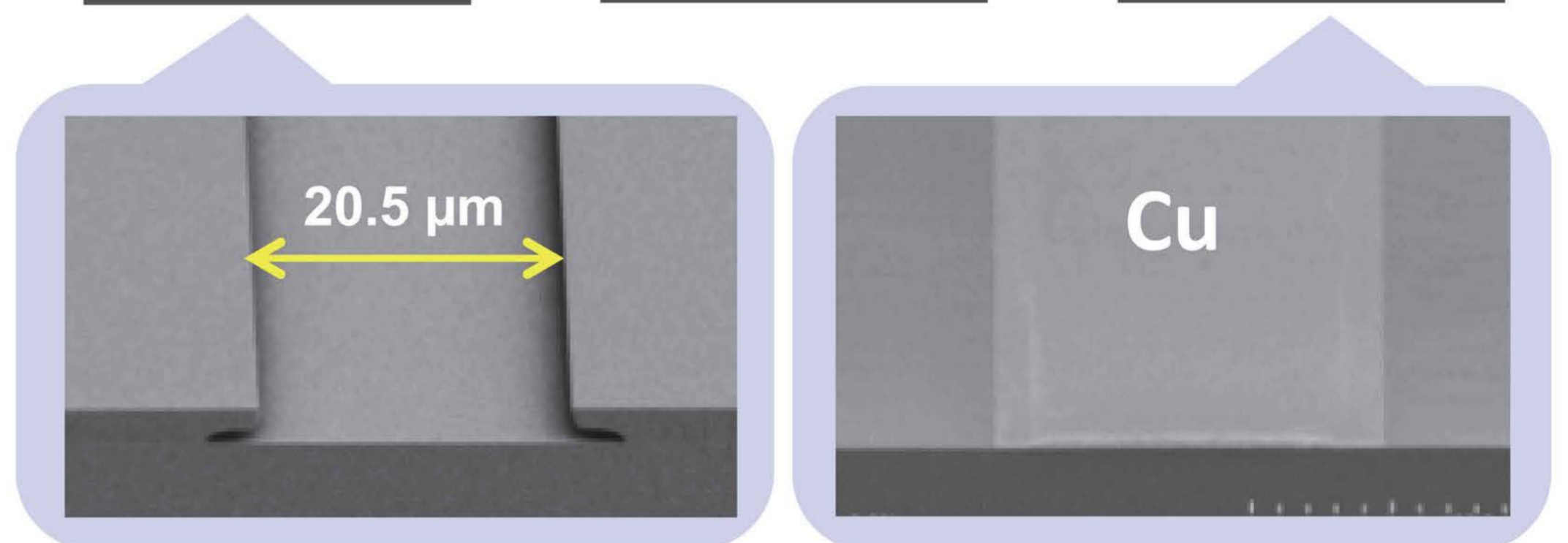
Solder Bump

JSR LUMILON™

LP series Photoresist for Lift-off Process

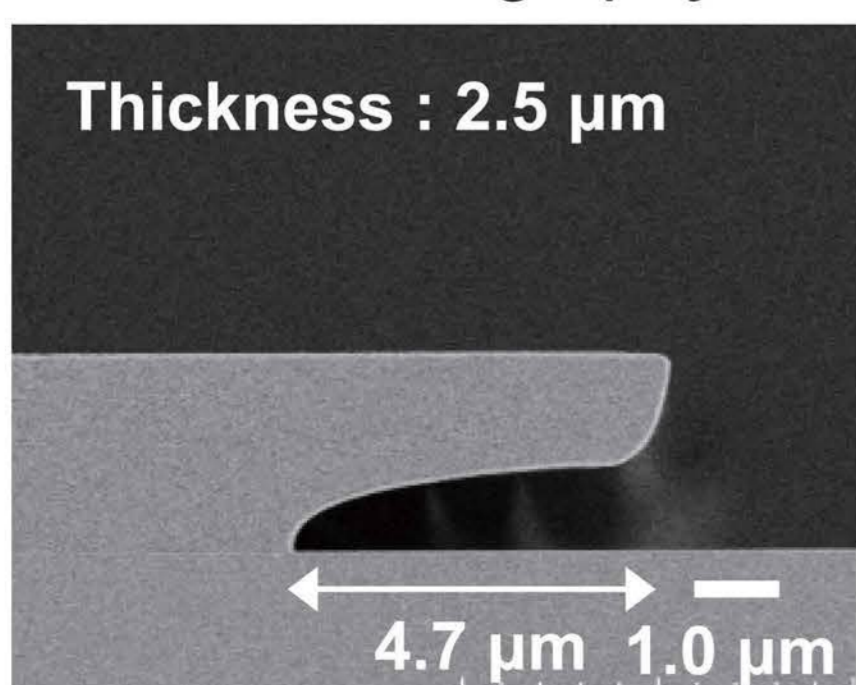
Features

- Ideal undercut profile
- Excellent strippability: NMP(RT)
- High thermal stability: 100 °C

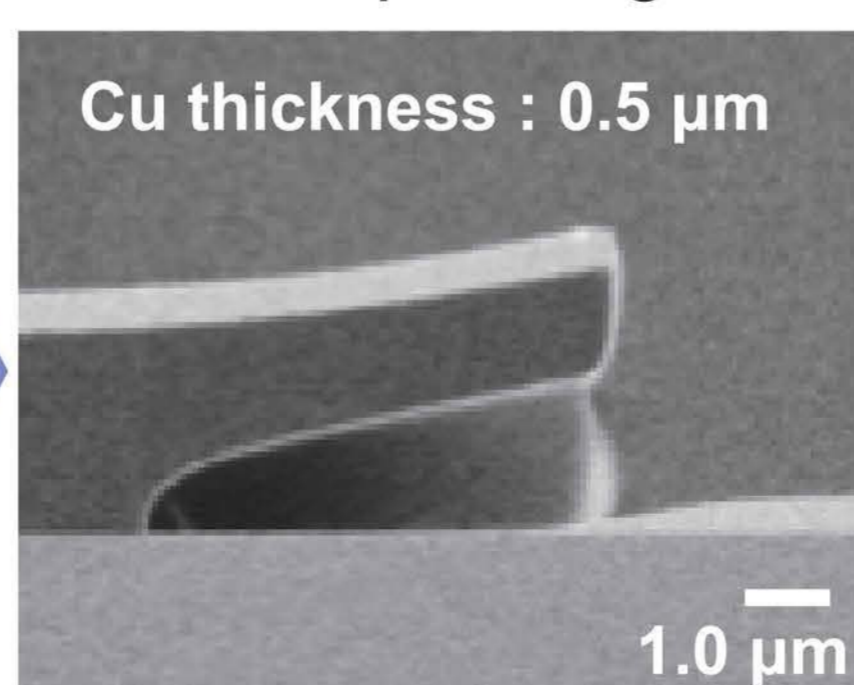


Single-layer (Negative-tone)

After lithography

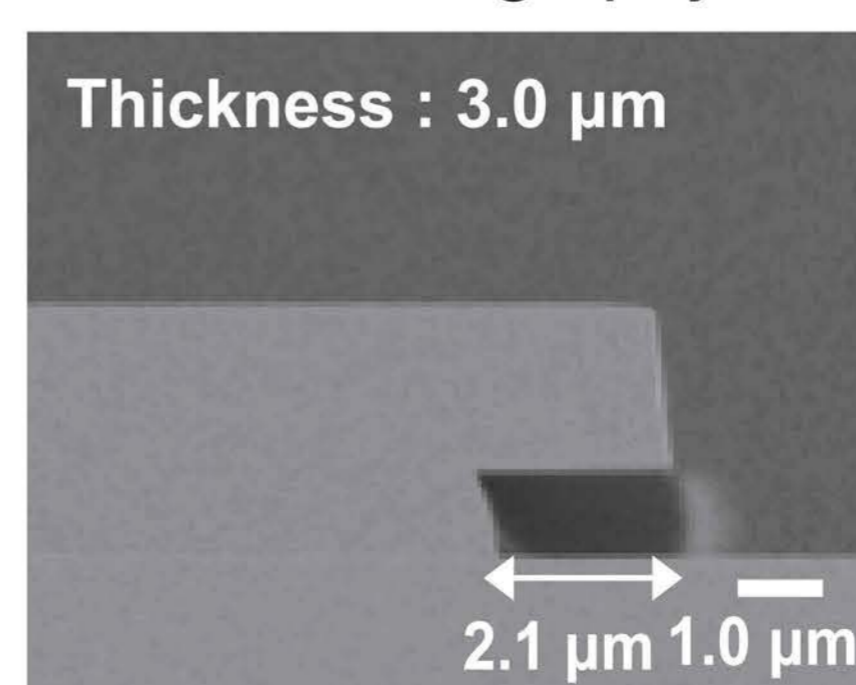


Cu sputtering



Double-layer (Positive-tone)

After lithography



Cu sputtering

